

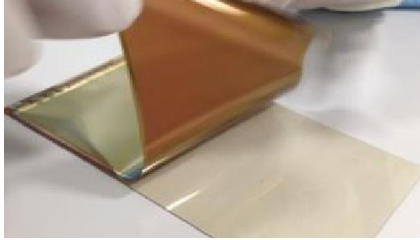
LLO Labo Kit

UV laser LLO R&D system LSL-10

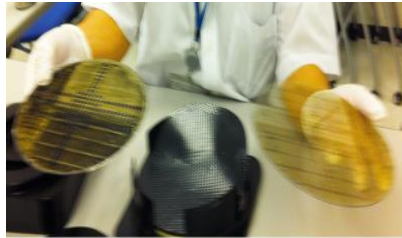


Application

- LLO for Flexible OLED
- LLO for ultra thin Si wafer
- LLO for organic semiconductor device
- LLO for flexible device as sensor and detector



Flexible display
(Courtesy INNOVAVENT)



Ultra thin Si wafer



Flexible organic device

Feature of the system

Using DPSS UV Laser with special optics unit to make homogeneous Line Beam to irradiate the work by moving X-Y stage to LLO for whole area as R&D purpose.

1. Very Low Price and ultra compact system
2. Can be use with 100V AC only. (less than 15A)
3. Option for Laser Film Cutting

Specification

Wavelength	355nm
Line beam size	10mm x 1mm
Process energy density	40~400mJ/cm ² (Variable attenuator)
Beam Overlap	Beam Overlap 0%~98% (Stage control)
Work size(mm)	Max150 x150 Option : G2(370 x470)
Process speed	5 min (100mm panel)
Stage stroke	200mm x200mm
System size (mm)	L1200 x W900 x H1300
Utility	AC100V ±10% 15A

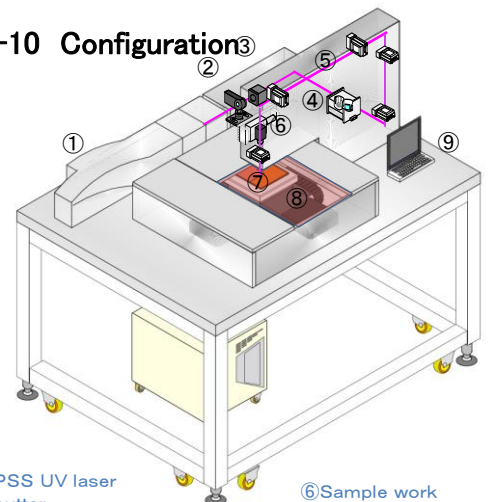


LSL-10 Lab Kit



LSO (1 scan)

LSL-10 Configuration



- ① DPSS UV laser
- ② Shutter
- ③ Energy monitor
- ④ Variable attenuator
- ⑤ Line beam optics

- ⑥ Sample work
- ⑦ X-Y stage
- ⑧ System controller

Note: The system use class 4 laser.
Therefore, laser safety measures are taken by the cover / interlock.

